This revision	(See MIL-STD-48	REVISION (NOR) of of instructions) een authorized for the document listed	DATE (YYMMDD) 1. 93/03/22	Form Approved OMB No.0704-0188				
Public reporting burden for this collection is estimated to average 1 hour per response, including the time for reviewing instructions, searching existing data sources, gathering and maintaining the data needed, and completing and reviewing the collection of information. Send comments regarding this burden estimate or any other aspect of this collection of information, including suggestions for reducing this burden, to Washington Headquarters Services, Directorate for Information Operations and Reports, 1215 Jefferson Davis Highway, Suite 1204, Arlington, VA 22202-4302, and to the Office of Information and Regulatory Affairs, Office of Management and Budget, Washington, DC 20503.								
1. ORIGINATOR NAME AND ADDRESS Defense Electronics Supply Center Dayton, Ohio 45444-5277 2. CAGE CODE 3. NOR NO. 67268 5962-R095-93								
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			4. CAGE CODE	5. DOCUMENT NO.				
			67268	5962-87704				
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			8. ECP NO.					
9. CONFIGUR	ATION ITEM (OR SYSTE	EM) TO WHICH ECP APPLIES						
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10. DESCRIP	TION OF REVISION							
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Sheet 2:		num ratings; DC output current per 5, 06 change from: +100 mA (2 x I _{OL} to: -100 mA						
	Absolute maximum ra for device types 05	atings; DC output current per pin: 5, 06 change from: +100 mA (2 x I _{OH} to: -100 mA	I _{SOURCE} ,					
	Revision level bloc	ek; add "C".						
11. THIS SE	CTION FOR GOVERNMENT	USE ONLY						
• •	CUMENT SUPPLEMENTED R MAY BE USED IN E.	[] REVISED DOCUMENT MUST BE RECEIVED BEFORE MANUFACTURER MAY INCORPORATE THIS CHANGE.	[] CUSTODIAN OF MASTER DO SHALL MAKE ABOVE RI FURNISH REVISED DOO	EVISION AND				
	UTHORIZED TO APPROVE R GOVERNMENT	SIGNATURE AND TITLE Monica L. poelking	DATE (YYMMDD)					
DESC-ECS		CHIEF MICROELECTRONICS BRANCH	93/03/22					
12. ACTIVITY REVISION	ACCOMPLISHING	REVISION COMPLETED (Signature) Jeffery Tunstall	DATE (YYMMDD)					

DESC-ECC

93/03/22

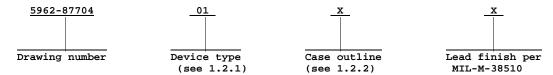
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SHEET 1 OF 14

1. SCOPE

1.1 <u>Scope</u>. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".

1.2 Part or Identifying Number (PIN). The complete PIN shall be as shown in the following example:



1.2.1 <u>Device type(s)</u>. The device type(s) shall identify the circuit function as follows:

<u>Device type</u>	Generic number	<u>Circuit function</u>
01	29C861	High performance CMOS 10-bit bus transceiver
02	29C863	High performance CMOS 9-bit bus transceiver
03	29C961	High performance CMOS 10-bit bus transceiver (rotated die) $\frac{1}{2}$
04	29C963	High performance CMOS 9-bit bus transceiver (rotated die) $\frac{1}{2}$ /
05	29C861A	High performance CMOS 10-bit bus transceiver
06	29C863A	High performance CMOS 9-bit bus transceiver

1.2.2 Case outline(s). The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
K	GDFP2-F24 or CDFP3-F24	24	Flat pack
L	GDIP3-T24 or CDIP4-T24	24	Dual-in-line
3	CQCC1-N28	28	Square leadless chip carrier

1.2.3 <u>Lead finish</u>. The lead finish shall be as specified in MIL-M-38510. Finish letter "X" shall not be marked on the microcircuit or its packaging. The "X" designation is for use in specifications when lead finishes A, B, and C are considered acceptable and interchangeable without preference.

1.3 Absolute maximum ratings.

```
-0.5 V dc to +7.0 V dc
                                                           -0.5 V dc to 6.0 V dc
-0.5 V dc to 6.0 V dc
                                                           +50 mA
                                                           -50 mA
DC input diode current: into input - - - - - - - DC input diode current: out of input - - - - - - -
                                                           +20 mA
                                                            -20 mA
DC output current per pin: I<sub>SINK</sub>
 +48 mA (2 x I_{OL})
                                                            +100 \text{ mA} (2 \times I_{OL})
DC output current per pin: I_{\text{SOURCE}}
  -30 mA (2 \times I<sub>OH</sub>)
                                                            -100 mA (2 x I_{OH})
Total dc ground current - - - - - - - - - - - -
                                                            (n \times I_{OL} + m \times I_{CCT}) mA

(n \times I_{OH} + m \times I_{CCT}) mA

-65^{\circ}C to +150^{\circ}C
Total dc V<sub>CC</sub> current- - - - - - - - - - - - - -
Storage temperature range - - - - - - - - - -
Maximum power dissipation P_D 3/----- Lead temperature (soldering, 10 seconds)-----
                                                            500 mW
                                                            +300°C
Thermal resistance, junction-to-case (\Theta_{JC}):
 Cases K, L, and 3 - - - - - - - - - - - - -
                                                            See MIL-STD-1835
Junction temperature (T_J) - - - - - - - - - - - -
                                                           +150°C
```

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[/] Not available from an approved source of supply.

 $[\]frac{1}{2}$ / n = number of outputs, m = number of inputs.

 $[\]overline{\underline{3}}$ / For T_A = +100°C to +125°C derate linearly at 10 mW/°C.

1.4 Recommended operating conditions.

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and bulletin. Unless otherwise specified, the following specification, standards, and bulletin of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MTT.TTARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.
MIL-STD-1835 - Microcircuit Case Outlines.

BULLETIN

MILITARY

MIL-BUL-103 - List of Standardized Military Drawings (SMD's).

(Copies of the specification, standards, and bulletin required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
 - 3.2.1 <u>Case outline(s)</u>. The case outline(s) shall be in accordance with 1.2.2 herein.
 - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.
 - 3.2.3 <u>Truth table(s)</u>. The truth table(s) shall be as specified on figure 2.
 - 3.2.4 Logic diagram(s). The logic diagram(s) shall be as specified on figure 3.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

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Test	Symbol			Group A subgroup	Device type	Li	mits	Unit
		$4.5 \text{ V} \leq \text{V}_{C}$	$4.5 \text{ V} \leq \text{V}_{\text{CC}} \leq 5.5 \text{ V}$ unless otherwise specified			Min	Max	
High level output voltage	v _{OH}	$V_{CC} = 4.5 \text{ V}$ $V_{IN} = V_{IL} \text{ or } V_{IH}$	I _{OH} = -15 mA	1, 2, 3	All	2.4		v
Low level output voltage	v_{ol}	$V_{CC} = 4.5 \text{ V}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$	I _{OL} = 24 mA	1, 2, 3	01-04		0.5	v
		I _{OL} = 32 mA		05,06				
Input clamp voltage	v _{ic}	V _{CC} = 4.5 V	I _{IN} = -18 mA	1, 2, 3	All		-1.2	v
Low level input	I _{IL1}	V _{CC} = 5.5 V Input only	V _{IN} = 0 V	1, 2, 3	01-04		-10	μА
currenc		- Input Only			05,06		-5	
	I _{IL2}		V _{IN} = 0.4 V		01-04		-5	μА
High level input current	I _{IH1}	V _{CC} = 5.5 V Input only	V _{IN} = 2.7 V	1, 2, 3	01-04		5	μА
	I _{IH2}		V _{IN} = 5.5 V		01-04		10	μА
					05,06		5	
Off-state leakage current	I _{OZH1}	V _{CC} = 5.5 V I/O port	V _{OUT} = 2.7 V	1, 2, 3	01-04		15	μА
	I _{OZH2}		V _{OUT} = 5.5 V		01-04		20	μА
		_			05,06		10	
	I _{OZL1}		V _{OUT} = 0.4 V		01-04		-15	μА
	I _{OZL2}		V _{OUT} = 0 V		01-04		-20	μA
					05,06		-10	
Static supply	ICCO	v _{CC} = 5.5 v	V _{IN} = 5.5 V or 0 V	1,2,3	01-04		160	μА
current		Outputs open	Active output high		05,06		1.5	mA
	I _{CCT}		V _{IN} = 3.4 V Data				1.5	mA/bit
			OER1 OER2 OET1		All		3.0	mA/bit

See footnotes at end of table.

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	TABI	LE I. Electrical performance charact	<u>ceristics</u> -	Continue	1.		
Test	Symbol	Conditions $-55^{\circ}C \le T_{C} \le +125^{\circ}C$ 4.5 V \le V _{CC} \le 5.5 V	Group A subgroup	Device type	Li	imits	Unit
		unless otherwise specified		<u> </u>	Min	Max	
Output short circuit current	I _{sc}	V _{CC} = 5.5 V V _{OUT} = 0 V <u>1</u> /	1, 2, 3	ALL	-60		mA
Functional testing		See 4.3.1d	7,8	A11			
Input capacitance	C _{IN}	See 4.3.1c	4	All		16	pF
Output capacitance	C _{OUT}	See 4.3.1c	4	All		20	pF
I/O capacitance	C _{I/O}	See 4.3.1c	4	A11		20	pF
Propagation delay	t _{PLH}	See figure 4	9,10,11	01-04	<u> </u>	12	ns
from Ri to Ti or Ti to Ri		$C_{L} = 50 \text{ pF}$ $R_{1} = 500\Omega$ $R_{2} = 500\Omega$		05,06		8	
Propagation delay from Ri to Ti	t _{PHL}		9,10,11			12	ns
or Ti to Ri		+		05,06	-	9	
Ou <u>tpu</u> t enable time OET to Ti or	t _{PZH}		9,10,11	01-04		16	ns
OER to Ri				05	 	11	+
		+		06	 	11.5	<u> </u>
Ou <u>tpu</u> t enable time OET to Ti or	t_{PZL}		9,10,11	01-04		16	ns
OER to Ri				05,06		13.5	
Ou <u>tpu</u> t disable time	t _{PHZ}		9,10,11	01-04	<u> </u>	16	ns
<u>OET</u> to Ti or OER to Ri				05		10	
				06		11	
Output disable time OET to Ti or	t _{PLZ}		9,10,11	01-04		16	ns
OER to Ri				05		11	_
				06		12	

 $[\]underline{1}/$ Not more than one output shorted at a time. Duration should not exceed 100 ms.

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Device types 01 and 05 Case outlines K and L OER [1 $R_0 \square 2$ 23 T₀ 22 T₁ 21 T₂ 20 T T3 19 T₄ R₄ ☐ 6 $R_5 \square 7$ 18 T₅ R6 🗆 8 17 T₆ R7 9 16 T₇ R₈ | 10 15 T₈ R₉ [11 14 T₉ GND 12 13 DET



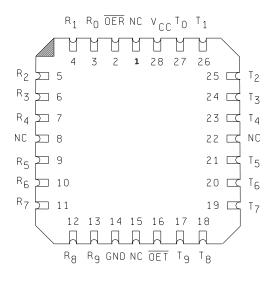


FIGURE 1. Terminal connections.

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Device types 02 and 06 Device types 02 and 06 Case outlines K and L Case outline 3 OER₁ [1 $R_0 \square 2$ 23 T₀ $R_1 \square 3$ 22 T₁ 3 2 **1** 28 27 26 . 25 ☐ T2 R₂ 4 21 T₂ R_3 ∑ 6 24 🖂 T₃ $R_3 \square 5$ 20 T T3 R₄ \(\sqrt{7}\) 23 🖂 74 19 T₄ 22 🖂 NC NC ≥ 8 $R_5 \searrow 9$ $R_5 \square 7$ 21 🖂 T₅ 18 🔲 T₅ R_6 20 □ 16 R6 🗆 8 17 T₆ **□** 10 R₇ \(\sqrt{11} \) 12 13 14 15 16 17 18 R7 49 16 T₇ R₈ ☐ 10 15 T₈ OER₂ ☐ 11 14 DET R8 OER 2 GND NC OET 1 OET 2 T8 GND [12 13 DET

FIGURE 1. Terminal connections - Continued.

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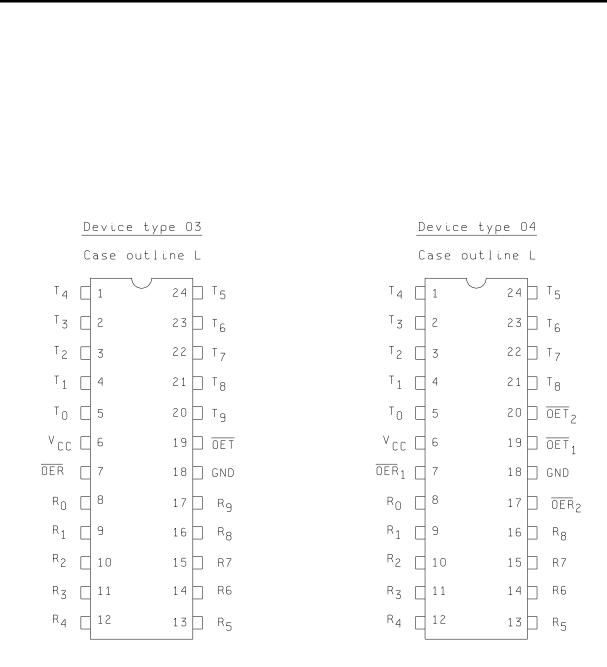


FIGURE 1. Terminal connections - Continued.

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Device types 02, 04, and 06

Device to	mee 01	ΛZ	and	Λ5

	In		puts		puts	
OET	OER	Ri	Ti	R _i	Ti	Function
L	н	L	N/A	N/A	L	Transmit
L	н	н	N/A	N/A	н	Transmit
Н	L	N/A	L	L	N/A	Receive
Н	L	N/A	н	н	N/A	Receive
н	н	х	x	z	z	Hi-Z

	Inputs Outputs					Outputs		Function
OET ₁	OET ₂	OER ₁	OER ₂	Ri	Ti	Ri	Ti	
L	L	н	х	L	N/A	N/A	L	Transmit
L	L	х	н	L	N/A	N/A	L	Transmit
н	х	L	L	N/A	L	L	N/A	Receive
х	Н	L	L	N/A	L	L	N/A	Receive
L	L	н	x	н	N/A	N/A	н	Transmit
L	L	х	Н	н	N/A	N/A	н	Transmit
н	х	L	L	N/A	н	н	N/A	Receive
x	н	L	L	N/A	н	н	N/A	Receive
н	х	н	х	х	х	Z	z	Hi-Z
х	Н	х	н	х	х	z	Z	Hi-Z

H = High

L = Low

Z = High impedance

X = Don't care

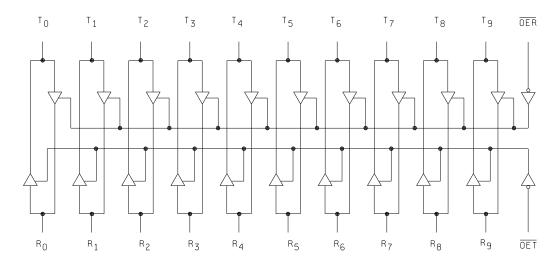
N/A = Not applicable

FIGURE 2. Truth tables.

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Device types 01, 03, and 05



Device types 02, 04, and 06

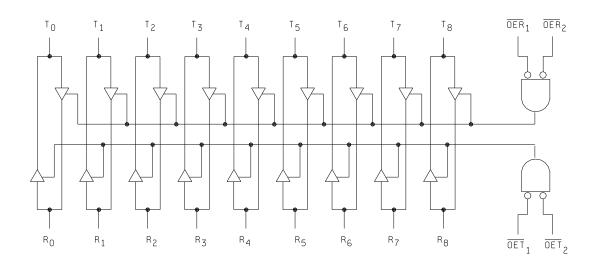
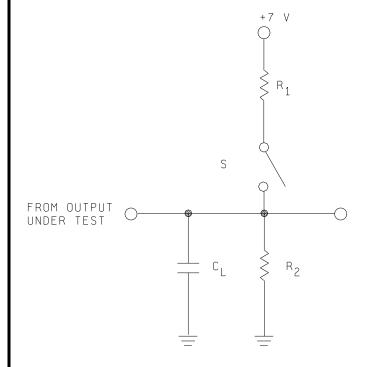


FIGURE 3. Logic diagrams.

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Parameter	S position
t _{PLH}	Open
t _{PHL}	Open
t _{PHZ}	Open
t _{PZH}	Open
t _{PLZ}	Closed
t _{PZL}	Closed

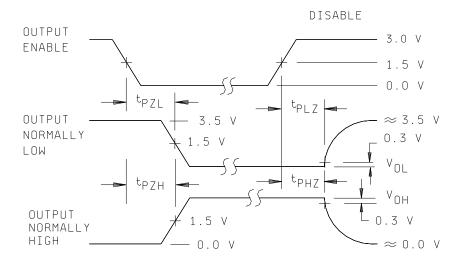
Switch positions for parameter testing

Load circuit for three-state outputs

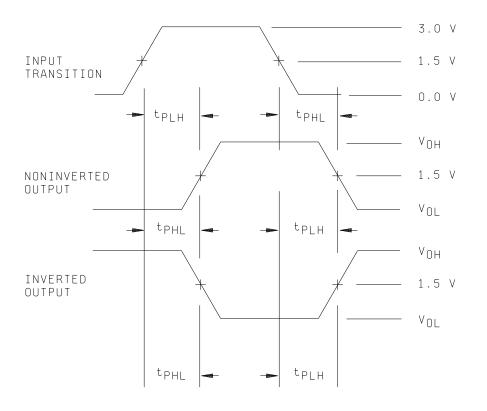
FIGURE 4. Switching circuits and waveforms.

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Enable and disable times



Propagation delay



FIGURE

4.

<u>Switching circuits and waveforms</u> - Continued.

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- 3.5 <u>Marking</u>. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-BUL-103 (see 6.6 herein).
- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-EC prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change</u>. Notification of change to DESC-EC shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.9 <u>Verification and review</u>. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
 - 4. OUALITY ASSURANCE PROVISIONS
- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall include the requirements for inputs, outputs, biases, and power dissipation, as applicable, in accordance with the specified purpose of method 1015.
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

TABLE II. <u>Electrical test requirements</u>.

MIL-STD-883 test requirements	Subgroups (in accordance with method 5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters (method 5004)	1*,2,3,7*,8,9,10,11
Group A test requirements (method 5005)	1,2,3,4,7,8,9,10,11
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

^{*} PDA applies to subgroup 1 and 7.

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- 4.3 <u>Quality conformance inspection</u>. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - c. Subgroup 4 (C_{IN} , C_{OUT} , and $C_{I/O}$ measurement) shall be measured only for the initial test and after process or design changes which may affect input capacitance.
 - d. Subgroups 7 and 8 shall include verification of the truth table.
 - 4.3.2 Groups C and D inspections.
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition A, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
 - 5. PACKAGING
 - 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.
 - 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for original equipment manufacturer application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-ECS, telephone (513) 296-6047.
- 6.5 <u>Comments</u>. Comments on this drawing should be directed to DESC-EC, Dayton, Ohio 45444, or telephone (513) 296-5377.
- 6.6 Approved sources of supply. Approved sources of supply are listed in MIL-BUL-103. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-EC.

STANDARDIZED MILITARY DRAWING	SIZE A		5962-87704
DEFENSE ELECTRONICS SUPPLY CENTER		REVISION LEVEL	SHEET
DAYTON, OHIO 45444		B	14

STANDARDIZED MILITARY DRAWING SOURCE APPROVAL BULLETIN

DATE:

Approved sources of supply for SMD 5962-87704 are listed below for immediate acquisition only and shall be added to MIL-BUL-103 during the next revision. MIL-BUL-103 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DESC-ECS. This bulletin is superseded by the next dated revision of MIL-BUL-103.

Standardized	Vendor	Vendor
military drawing	CAGE	similar
PIN	number	PIN <u>1</u> /
5962-8770401LX	34335	AM29C861/BLA
5962-8770401KX	34335	AM29C861/BKA
5962-87704013X	34335	AM29C861/B3A
5962-8770402LX	34335	AM29C863/BLA
5962-8770402KX	34335	AM29C863/BKA
5962-87704023X	34335	AM29C863/B3A
5962-8770403LX	<u>2</u> /	AM29C961/BLA
5962-8770404LX	<u>2</u> /	AM29C963/BLA
5962-8770405LX	34335	AM29C861A/BLA
5962-8770405KX	34335	AM29C861A/BKA
5962-87704053X	34335	AM29C861A/B3A
5962-8770406LX	34335	AM29C863A/BLA
5962-8770406KX	34335	AM29C863A/BKA
5962-87704063X	34335	AM29C863A/B3A

- <u>1</u>/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- $\underline{2}/$ Not available from an approved source of supply.

number	vendor name and address
34335	Advanced Micro Devices, Incorporated 901 Thompson Place P.O. Box 3453
	Sunnyvale, CA 94088

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in this information bulletin.